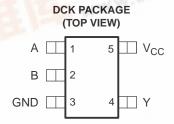
SCES679-JULY 2007

询**%♥♥₱₫⁰♥**C1G86-FP"供应商

FEATURES

- Controlled Baseline
 - One Assembly/Test Site, One Fabrication
- Extended Temperature Performance of -55°C to 125°C
- **Enhanced Diminishing Manufacturing Sources** (DMS) Support
- **Enhanced Product-Change Notification**
- Qualification Pedigree (1)
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 6.7 ns at 3.3 V
- Low Power Consumption, 15-µA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- I_{off} Supports Partial-Power-Down Mode Operation
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over specified temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental

- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

This single 2-input exclusive-OR gate is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G86 performs the Boolean function $Y = A \oplus B$ or $Y = \overline{AB} + A\overline{B}$ in positive logic.

A common application is as a true/complement element. If the input is low, the other input is reproduced in true form at the output. If the input is high, the signal on the other input is reproduced inverted at the output.

This device is fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION(1)

T _A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽³⁾	
-55°C to 125°C	SOT (SC-70) - DCK	Reel of 3000	SN74LVC1G86MDCKREP	CJ_	

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.
- (3) DCK: The actual top-side marking has one additional character that designates the assembly/test site.



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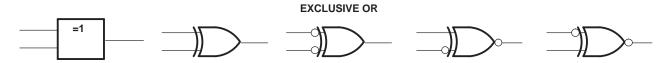


FUNCTION TABLE

INP	UTS	OUTPUT
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L

EXCLUSIVE-OR LOGIC

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These are five equivalent exclusive-OR symbols valid for an SN74LVC1G86 gate in positive logic; negation may be shown at any two ports.

SCES679-JULY 2007

查询"SN74LVC1G86-EP"供应商 Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
V_{CC}	Supply voltage range				6.5	V
VI	Input voltage range ⁽²⁾			-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾			-0.5	6.5	V
Vo	Voltage range applied to any output in the high or low state (2)(3)			-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0			-50	mA
I _{OK}	Output clamp current	V _O < 0			-50	mA
Io	Continuous output current				±50	mA
	Continuous current through V _{CC} or GND				±100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾				252	°C/W
T _{stg}	Storage temperature range			-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The value of V_{CC} is provided in the recommended operating conditions table.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

SN74LVC1G86-EP SINGLE 2-INPUT EXCLUSIVE-OR GATE





Recommended Operating Conditions(1)

			MIN	MAX	UNIT
V	Cumply yeltogo	Operating	1.65	5.5	V
V_{CC}	Supply voltage	Data retention only			V
		V _{CC} = 1.65 V to 1.95 V	0.65 X V _{CC}		
W	High level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
V_{IH}	High-level input voltage	V _{CC} = 3 V to 3.6 V	2		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0.7 X V _{CC}		
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		0.35 X V _{CC}	
V	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
V_{IL}	Low-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		8.0	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$0.3 \times V_{CC}$	
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V_{CC}	V
		V _{CC} = 1.65 V		-4	
		V _{CC} = 2.3 V		-8	
I_{OH}	High-level output current	V _{CC} = 3 V		-16	mA
		V _{CC} = 3 V		-24	
		V _{CC} = 4.5 V		-32	
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		8	
I_{OL}	Low-level output current	V _{CC} = 3 V		16	mA
		vcc = 3 v		24	
		V _{CC} = 4.5 V		32	
		V_{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20	
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 3.3 V \pm 0.3 V		ns/V	
		$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$			
T _A	Operating free-air temperature		-55	125	°C

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS	V		T _A = 25°C	-55°C to 125°C	UNIT
PARAMETER	TEST CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾ MAX	MIN MAX	ONIT
	I _{OH} = -100 μA	1.65 V to 5.5 V	V _{CC} - 0.1		V _{CC} - 0.1	
	I _{OH} = -4 mA	1.65 V	1.2		1.2	
V	I _{OH} = -8 mA	2.3 V	1.9		1.9	V
V _{OH}	$I_{OH} = -16 \text{ mA}$	3 V	2.4		2.4	V
	$I_{OH} = -24 \text{ mA}$	3 V	2.3		2.3	
	I _{OH} = -32 mA	4.5 V	3.8		3.8	
	I _{OL} = 100 μA	1.65 V to 5.5 V		0.1	0.1	
	I _{OL} = 4 mA	1.65 V		0.45	0.45	
V	$I_{OL} = 8 \text{ mA}$	2.3 V		0.3	0.3	V
V _{OL}	I _{OL} = 16 mA	3 V		0.4	0.4	
	I _{OL} = 24 mA			0.55	0.55	
	I _{OL} = 32 mA	4.5 V		0.55	0.55	
I _I A or B input	V _I = 5.5 V or GND	0 to 5.5 V		±5	±5	μΑ
I _{off}	V_I or $V_O = 5.5 \text{ V}$	0		±10	±10	μΑ
I _{CC}	$V_I = V_{CC} \text{ or } $ $I_O = 0$	1.65 V to 5.5 V		10	15	μΑ
Δl _{CC}		3 V to 5.5 V		500	500	μΑ
C _i	$V_I = V_{CC}$ or GND	3.3 V		6		pF

⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 ± 0.3 V	V _{CC} = 5 V ± 0.5 V		UNIT	
	(INFOI)	(001701)	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Y	1.3	6.7	1	5.7	ns

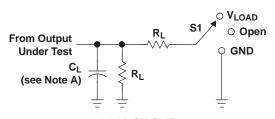
Operating Characteristics

 $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 3.3 V	V _{CC} = 5 V	UNIT
	PARAMETER	TEST CONDITIONS	TYP	TYP	UNIT
C_{pd}	Power dissipation capacitance	f = 10 MHz	22	24	pF



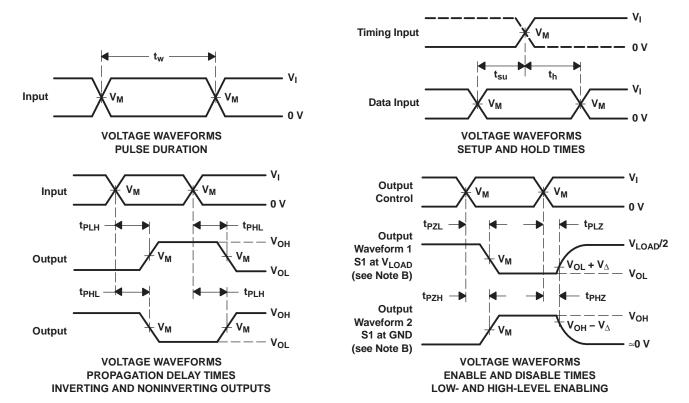
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

V	INPUTS		· ·	V			.,
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	R _L	$V_{\!\scriptscriptstyle\Delta}$
1.8 V \pm 0.15 V	v _{cc}	≤ 2 ns	V _{CC} /2	2×V _{CC}	15 pF	1 M Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	15 pF	1 M Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	15 pF	1 M Ω	0.3 V
5 V \pm 0.5 V	V _{CC}	≤2.5 ns	V _{CC} /2	2×V _{CC}	15 pF	1 M Ω	0.3 V

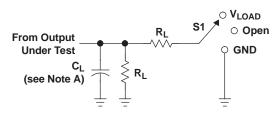


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

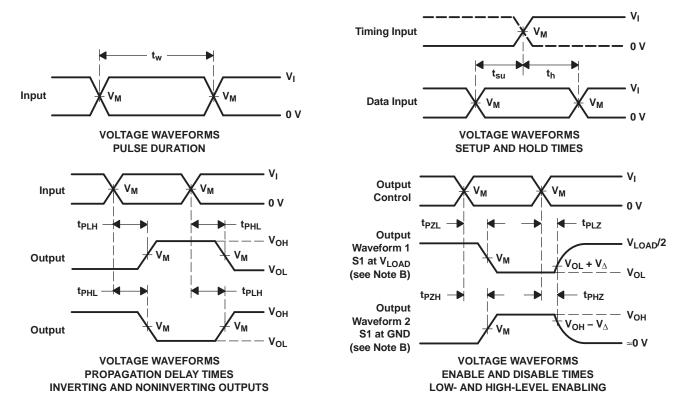
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

V	INPUTS		· ·	V			.,
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	R _L	$V_{\!\scriptscriptstyle\Delta}$
1.8 V \pm 0.15 V	v _{cc}	≤ 2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V \pm 0.5 V	V _{CC}	≤2.5 ns	V _{CC} /2	2×V _{CC}	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins P	ackage Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC1G86MDCKREP	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06666-01XE	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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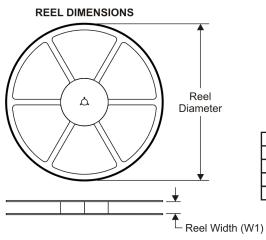
Catalog: SN74LVC1G86

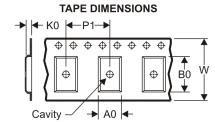
NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

11-Mar-2008

TAPE AND REEL INFORMATION





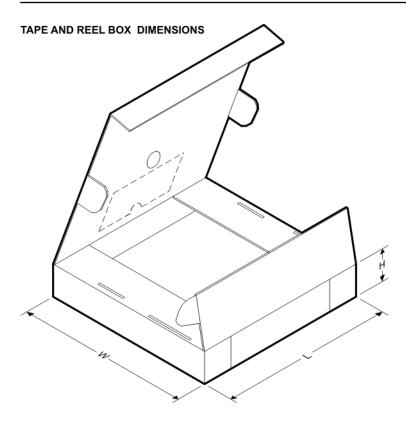
	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G86MDCKREP	SC70	DCK	5	3000	180.0	9.2	4.0	2.24	2.34	4.0	8.0	Q3

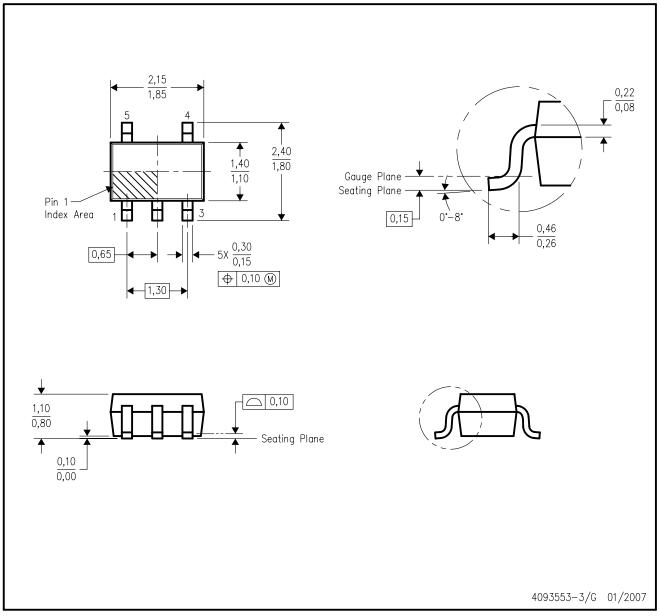


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G86MDCKREP	SC70	DCK	5	3000	202.0	201.0	28.0

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



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